

PATENT ABSTRACTS OF JAPAN

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(54) RESIN SEALING TYPE SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To eliminate the tab short-circuit of the resin sealed device by a method wherein a stepped section is provided on a side having a crossing point of the tab and a connection line.

CONSTITUTION: The stepped section 113a is provided on one main surface 111 of the tab 11 and, therefore, it has a smaller area than the other main surface 112. A lead piece 12 is located on the same plane surface as the tab 11. In this constitution, the tab short-circuit caused by a sagging of wire 14 can be prevented even when the tab 11 and the lead piece 12 are located on the same plane surface. When the tab is formed by performing a plastic processing, the peripheral portion of the stepped section 113a is protruding and this increases the adhesive strength of the resin 15 and the tab 11.



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